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MARK III B CONDUCTIVITY, TEMPERATURE, DEPTH PROFILER UNDERWATER UNIT

OPERATION AND MAINTENANCE

MANUAL 00101

JANUARY 1982

CUSTOMER _____

DATE _____ MJO _____

This volume is designed as a complete guide to the use and maintenance of the **Neil Brown Instrument Systems, Inc. Mark IIIB CTD Profiler**, and consists of the following manuals:

Manual (Part #)	Title
[]	MANUL-00101 Mark IIIB CTD Profiler UWU
[]	MANUL-00102 Option 01: Oxygen Interface CTD UWU
[]	MANUL-00103 Option 02: 16-channel, 12-bit Digitizer CTD UWU
[]	MANUL-00104 Option 14: 2-channel, 12-bit Digitizer CTD UWU
[]	MANUL-00105 Bottom Contact Switch option CTD UWU
[]	MANUL-00106 Altimeter Interface option CTD UWU
[]	MANUL-00107 Fast Temperature Digitizing option CTD UWU
[]	MANUL-00108 Combining End Cap for G.O. Rosette CTD UWU
[]	MANUL-01401 Internal Recording CTD (CTD/IR)
[]	MANUL-01402 Memodyne Model 201 Recorder (CTD/IR)
[]	MANUL-01501 Model 1350 Sea Cable Supply
[]	pH option CTD UWU
[]	N/A NBIS product specification sheets

NOTE

Manual 00101 describes the basic CTD underwater unit (UWU) only; manuals relating to specific options, where ordered, are inserted separately in this volume and identified by the suffix of the part number shown above.

STANDARD COMMERCIAL WARRANTY

All equipment manufactured by Neil Brown Instrument Systems, Inc. is warranted against defective components and workmanship for repair at the plant in Cataumet, Massachusetts free of charge for a period of one year after shipment. Malfunction due to improper use is not covered in this warranty. Shipping costs are to be borne by the customer.

LIMITED LIABILITY STATEMENT

Extreme caution should be exercised when using this equipment; it should not be used or serviced except by personnel with a special knowledge of and training in the use and maintenance of oceanographic electronic equipment.

Neil Brown Instrument Systems, Inc. disclaims any liability for consequential damage resulting from defects in the performance of this equipment.

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